ASML 300C DUV Stepper

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Backup: John Treichler
Backup: 254-4936
Backup: 254-4949

Safety
- None

Process Restrictions

Material Restrictions
- Standard wafers ONLY based on current tool configuration
- Carrier wafers MUST be approved by Photolith staff
- Back of substrate must be CLEAN - NO RESIST on back
- Mask must be CLEAN - no resist or fingerprints

Parameter Restrictions
- Die size 22mm x 22mm, or 14.7mm x 27.4mm
- Standard ASML fiducial marks MUST be used

Scheduling / Sign-up Restrictions -- Minimum Tool Time: 30 minutes
- First time runs with staff ONLY - Maximum 3 hour block reservations during daytime - Maximum 6 hours reserved in advance at any time per person - No consecutive research group reservations - Users/Groups may use any amount of unreserved time - Additional individual restrictions may be imposed to maximize effective use

Requirements (Do Every Time)
- Clean backside of all wafers
- Consult staff before loading reticles
- Use wafer carriers supplied at tool
- Log out of ASML software and CORAL when finished

Prohibitions (Never Do)
- NEVER leave reticles or wafers in tool
- NEVER load dirty wafers or reticles
- NEVER load wafers any size other than tool is configured for

Common Problems
<table>
<thead>
<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
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Other Comments or Cautions

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.